

Amendments to the Claims:

The following **Listing of Claims** will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1 - 12 (previously canceled).

Claims 13 – 15 (cancelled).

Claim 16 (previously cancelled).

Please add the following **new** claims:

17. (new) A method of making a printed circuit board, said method comprising:

providing a first multilayered portion including at least one dielectric layer having a dielectric constant and at least one conductive plane wherein said conductive plane includes signal lines capable of having signals pass there-along at a first frequency; and

providing a second multilayered portion adapted for having a plurality of electronic components electrically coupled thereto, said second multilayered portion including at least one dielectric layer having a dielectric constant lower than said dielectric constant of said first dielectric layer and at least one conductive signal plane wherein said conductive signal plane of said second multilayered portion includes signal lines capable of having signals pass there-along at a higher frequency than said first frequency to thereby provide a high speed connection between at least two of said electrical components; and

bonding said first and second multilayered portions together.

18. (new) The method of claim 17 further including providing a conductive through hole within said second multilayered portion prior to said bonding of said first and second multilayered portions.
19. (new) The method of claim 17 wherein said bonding is accomplished by lamination.
20. (new) A method of making a printed circuit board, said method comprising:

providing a first multilayered portion including at least one dielectric layer having a loss factor and at least one conductive plane wherein said conductive plane includes signal lines capable of having signals pass there-along at a first frequency;

providing a second multilayered portion adapted for having a plurality of electronic components electrically coupled thereto, said second multilayered portion including at least one dielectric layer having a lower loss factor than said loss factor of said dielectric layer of said first multilayered portion and at least one conductive signal plane wherein said conductive signal plane of said second multilayered portion includes signal lines capable of having signals pass there-along at a higher frequency than said first frequency to thereby provide a high speed connection between at least two of said electrical components; and

bonding said first and second multilayered portions together.
21. (new) The method of claim 20 further including providing a conductive through hole within said second multilayered portion prior to said bonding of said first and second multilayered portions.

22. (new) The method of claim 20 wherein said bonding is accomplished by lamination.

23. (new) A method of making a printed circuit board, said method comprising:

providing a first multilayered portion including at least one dielectric layer and at least one conductive plane wherein said conductive plane includes signal lines capable of having signals pass there-along at a first frequency;

providing a second multilayered portion adapted for having a plurality of electronic components electrically coupled thereto, said second multilayered portion including a conducting plane, first and second dielectric layers on opposite sides of said conducting plane, and two conductive signal planes, each conductive signal plane including signal lines capable of having signals pass there-along at a higher frequency than said first frequency to thereby provide a high speed connection between at least two of said electrical components, said two conductive signal planes being positioned, respectively, on said first and second dielectric layers opposite said conducting plane, said second multilayered portion further including a conductive through hole interconnecting at least one of said signal lines of a first of said two conductive signal planes to at least one of said signal lines of the second of said conductive signal plane;

providing a third dielectric layer on said second dielectric layer and said conductive signal plane positioned thereon, said third dielectric layer including at least one opening therein exposing at least one of said signal lines on said conductive signal plane positioned on said second dielectric layer such that at least one of said electrical components can be electrically coupled thereto; and

bonding said first and second multilayered portions.

24. (new) The method of claim 23 further including providing a conductive through hole within said second multilayered portion prior to said bonding of said first and second multilayered portions.
25. (new) The method of claim 23 wherein said bonding is accomplished by lamination.
26. (new) The method of claim 23 further including providing a layer of conductive material on said at least one opening.
27. (new) The method of claim 23 further including providing a conductive plane on said third dielectric layer.
28. (new) The method of claim 27 further including providing a fourth dielectric layer on said third dielectric layer and on said conductive plane located on said third dielectric layer, said fourth dielectric layer including at least one opening therein exposing said at least one opening in said third dielectric layer.